

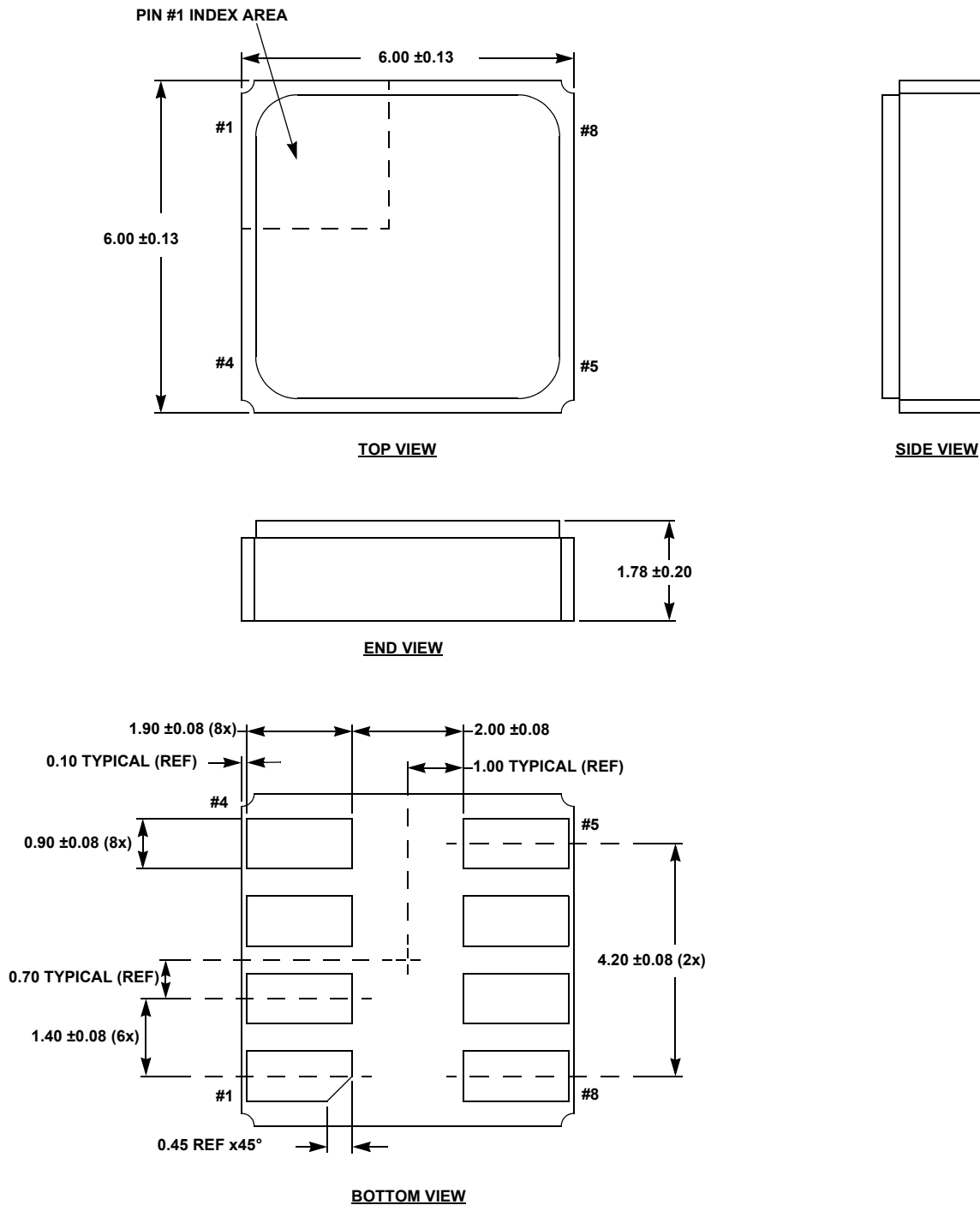
# Hermetic Packages for Integrated Circuits

## Package Outline Drawing

### J8.A

8 PIN 6mmx6mm HERMETIC SURFACE MOUNT PACKAGE

Rev 0, 3/16

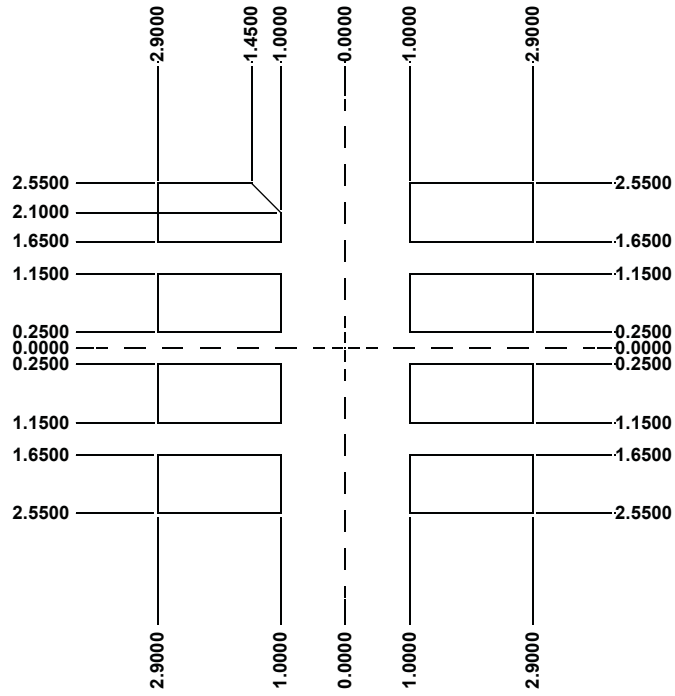


#### NOTES:

1. The corner shape (radius, chamfer, etc.) may vary at the manufacturers option from that shown on the drawing.
2. The package thickness dimension is the package height before being solder dipped.
3. Dimensions are in millimeters.

# Hermetic Packages for Integrated Circuits

---



TYPICAL RECOMMENDED LAND PATTERN